



DMN32D2LDF

COMMON SOURCE DUAL N-CHANNEL ENHANCEMENT MODE FIELD EFFECT TRANSISTOR

Features

- Common Source Dual N-Channel MOSFET
- Low On-Resistance
- Very Low Gate Threshold Voltage, 1.2V max
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Small Surface Mount Package
- ESD Protected Gate
- Lead Free By Design/RoHS Compliant (Note 2)
- "Green" Device (Note 3)
- Qualified to AEC-Q 101 Standards for High Reliability



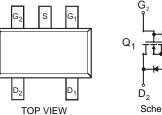


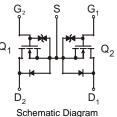


SOT-353

Mechanical Data

- Case: SOT-353
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.006 grams (approximate)





Maximum Ratings Q_1 , Q_2 @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
Drain Source Voltage	V_{DSS}	30	V	
Gate-Source Voltage	V_{GSS}	±10	V	
Drain Current (Note 1)	I_{D}	400	mA	

Thermal Characteristics Q₁, Q₂ @T_A = 25°C unless otherwise specified

Total Power Dissipation (Note 1)	P _D	280	mW
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ hetaJA}$	446	°C/W
Operating and Storage Temperature Range	T_j,T_STG	-55 to +150	°C

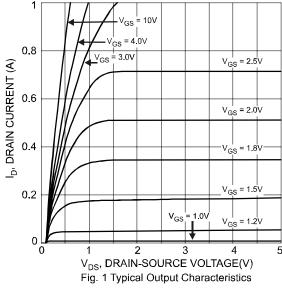
Electrical Characteristics Q_1 , Q_2 @ $T_A = 25$ °C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 4)		'					
Drain-Source Breakdown Voltage		BV _{DSS}	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current	@ T _C = 25°C	I _{DSS}	_		1	μА	$V_{DS} = 30V, V_{GS} = 0V$
Gate-Body Leakage			_	_	±10 ±1	μΑ	$V_{GS} = \pm 10V, V_{DS} = 0V$ $V_{GS} = \pm 5V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage		V _{GS(th)}	0.6	_	1.2	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
			_	_ _	2.2	Ω	$V_{GS} = 1.8V, I_D = 20mA$
Static Drain-Source On-Resistance		R _{DS} (ON)	_	_	1.5		$V_{GS} = 2.5V, I_D = 20mA$
			_	_	1.2		$V_{GS} = 4.0V, I_D = 100mA$
Forward Transconductance			100	_	_	mS	$V_{DS} = 10V, I_D = 0.1A$
Source-Drain Diode Forward Voltage			0.5	_	1.4	V	$V_{GS} = 0V, I_{S} = 115mA$
DYNAMIC CHARACTERISTICS							
Input Capacitance			_	39	_	pF)/ O)/)/ O)/
Output Capacitance			_	10	_	pF	$V_{DS} = 3V, V_{GS} = 0V$ f = 1.0MHz
Reverse Transfer Capacitance				3.6	_	pF	71 - 1.0141112
Switching Time	Turn-on Time	t _{on}	_	11	_	nS	$V_{DD} = 5V, I_D = 10 \text{ mA},$
Switching Time	Turn-off Time	t _{off}	_	51	_	nS	$V_{GS} = 0-5V$

Notes: 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

- 2. No purposefully added lead.
- 3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
 - . Short duration pulse test used to minimize self-heating effect.





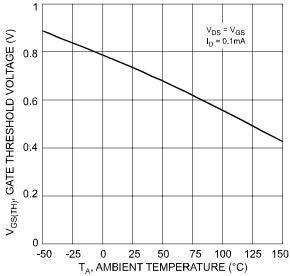


Fig. 3 Gate Threshold Voltage vs. Ambient Temperature

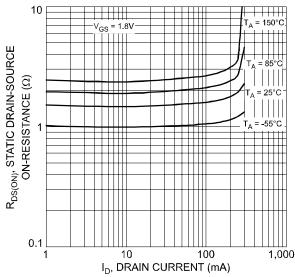
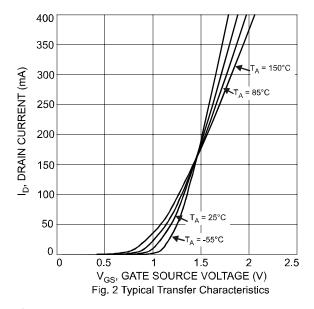


Fig. 5 Static Drain-Source On-Resistance vs. Drain Current



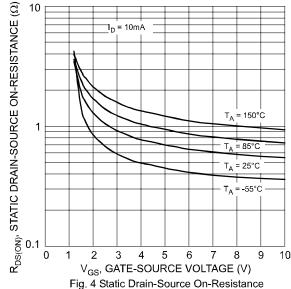


Fig. 4 Static Drain-Source On-Resistance vs. Gate-Source Voltage

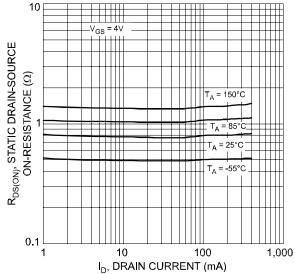


Fig. 6 Static Drain-Source On-Resistance vs. Drain Current



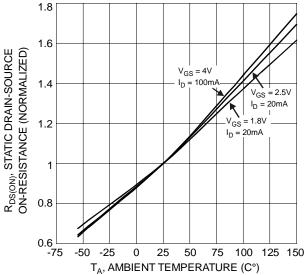


Fig. 7 Normalized Static Drain-Source On-Resistance vs. Ambient Temperature

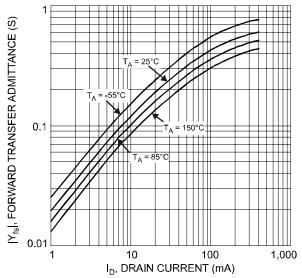


Fig. 9 Forward Transfer Admittance vs. Drain Current

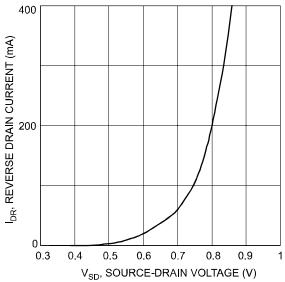
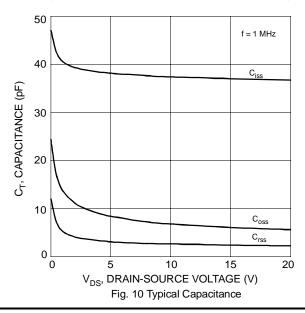


Fig. 8 Reverse Drain Current vs. Source-Drain Voltage

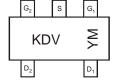


Ordering Information (Note 5)

Part Number	Case	Packaging
DMN32D2LDF-7	SOT-353	3000/Tape & Reel

Notes: 5. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information (Note 6)



KDV = Product Type Marking Code (See Note 6) YM = Date Code Marking

YM = Date Code Marking Y = Year ex: U = 2007

M = Month ex: 9 = September

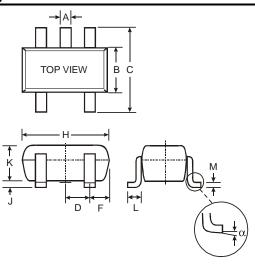
Notes: 6. Package is non-polarized. Parts may be on reel in orientation illustrated, 180° rotated, or mixed (both ways).

Date Code Key

Year	20	07	20	08	20	09	20	10	20	11	20	12
Code	l	J	\	/	٧	V	>	<	`	′	2	7
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

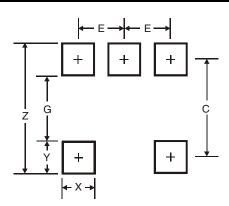


Package Outline Dimensions



	SOT-353					
Dim	Min	Max				
Α	0.10	0.30				
В	1.15	1.35				
С	2.00	2.20				
D	0.65 Nominal					
F	0.30	0.40				
Н	1.80	2.20				
J	_	0.10				
K	0.90	1.00				
L	0.25	0.40				
М	0.10	0.25				
α	0°	8°				
All Di	All Dimensions in mm					

Suggested Pad Layout



Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Υ	0.6
С	1.9
Е	0.65

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